

REMARKS

Claims 1-3, 5, 8 and 30 are pending in this application. It is requested that claim 33 also be included in this application.

The applicants traverse the withdrawal of claim 33 because claim 33 and claim 8 are the same but for the scope of the preamble. The preamble of claim 8 concerns a disk unit and wiring information to a disk, while the preamble of claim 33 concerns a unit which writes information to a recording medium. The three elements of each claim are exactly the same with the only difference being the indirect reference to the disk and the recording medium in the body of claim 8 and 33 respectively.

Since the object being worked on, namely the disk or recording medium, is not apart of the claim and the only other difference lies in the scope of the preamble, it is urged that claims 8 and 33 should be prosecuted together. Claim 33 could be considered generic to Claim 8. Therefore the applicants urge the Examiner to reconsider the withdrawal of claim 33 and enclose amended claim 33 for the Examiner's review assuming that claim 33 will be reconsidered in this application.

The amendments to the claims are supported in the specification as follows: Claims 1, 8 and 33 (p.14, lines 8-15; FIGS. 1, 2A and 7A).

The amendments further clarify the current claim language and do not present additional limitations that would require an additional search. It is urged that in this case, the claims be considered allowable, after final, based on the showing below.

Claims 1 and 30 stand rejected under 35 U.S.C. 102 (e) as being anticipated by **Ohwe '944**.

In view of this rejection, claim 1 is amended to further clarify the subject matter of the claimed invention. **Ohwe '944** proposes a head assembly having a head slider and an integrated circuit chip. However, the head slider **90** and the integrated circuit chip **100E** are mounted on opposite surfaces of the gimbal as shown in Fig. 16. This is because the height of the integrated circuit chip, when coated with a resin layer, would become higher than the head slider **90** if the head slider **90** and the integrated circuit chip **100E** were mounted on the same surface of the gimbal, thereby making the head assembly inoperative (that is, the integrated circuit chip would contact the recording medium before the head slider).

If the resin layer were to be provided on the integrated circuit chip in **Ohwe '944** and this integrated circuit chip were to be mounted on the same surface of the gimbal as the head slider, the height of the integrated circuit chip would exceed the height of the head slider.

In **Ohwe '944**, for the head assemblies having the head slider and the integrated circuit chip provided on the same mounting surface, the resin layer is not provided on the integrated circuit chip, as is evident from **Ohwe '944**. This is because the resin layer is too thick.

On the other hand, the claimed invention provides the head slider and the integrated circuit chip on the same mounting surface, and at the same time, the integrated circuit chip has an upper surface portion covered by a layer so that a height of the integrated circuit chip, including the layer, is lower than a height of the head slider from the mounting surface (p.16, lines 7-25).

Ohwe '944 does not teach or suggest such a height relationship of the head slider and the

integrated circuit chip on the same mounting surface, and does not teach or suggest the above described structure according to the invention as now claimed.

Accordingly, it is believed that claims 1 and 30 are allowable over **Ohwe '944**.

Claims 1-3, 5 and 8 stand rejected under 35 U.S.C. 103 (a) as being unpatentable over **Shiraishi '062** in view of **Shiraishi '746**.

In view of this rejection, claims 1 and 8 are amended to further clarify the subject matter of the claimed invention. As argued previously, **Shiraishi '062** fails to teach or suggest covering the integrated circuit chip by a layer to prevent generation of foreign particles, in order to solve the problems of the prior art described on page 2, line 11 to page 3, line 9 of the specification. Further, as noted by the Examiner, **Shiraishi '062** is silent as to the integrated circuit chip height, including the layer, being lower than a height of the head slider from the mounting surface.

Shiraishi '746 is relied upon as teaching the height of the integrated circuit chip being lower than the height of the head slider from the mounting surface. However, as argued previously, the object of **Shiraishi '062** is to improve the mechanical impact resistance of the head IC chip (integrated circuit chip). In order to achieve this object, it is essential in **Shiraishi '062** to provide a thick shock absorption layer **25**. Otherwise, the mechanical impact resistance of the head IC chip **13** cannot be achieved. In addition, it would be essential in **Shiraishi '062** to provide a projecting layer portion of the shock absorption layer **25** at the top peripheral edges of the head IC chip **13** in order to improve the mechanical impact resistance of the head IC chip **13**, as may be seen from Fig.

3, thereby making it impossible to make the height of the head IC chip 13, including the shock absorption layer 25, lower than the height of the head slider.

In other words, even if the teachings of **Shiraishi '062** and **Shiraishi '746** were combined, this combination would only lead to a result similar to that described above with reference to **Ohwe '944**. More particularly, the height of the head IC chip 13 including the shock absorption layer 25 of **Shiraishi '062** would become higher than that of the head slider 12, because the thickness of the shock absorption layer 25 simply cannot be reduced. The only way to prevent the head IC chip 13 from contacting the recording medium is to provide the head IC chip 13 and the head slider 12 on opposite surfaces of the gimbal, as in the case of **Ohwe '944**.

With respect to the chip covering layer, those skilled in the art would most certainly not consider or use poly(p-xylylene) in **Shiraishi '046**, because such a material cannot function as a shock absorption layer 25 and cannot achieve the object of **Shiraishi '046** which is to improve the mechanical impact resistance of the head IC chip 13 .

Therefore, it is believed that claims 1-3, 5 and 8 are allowable over the combination of **Shiraishi '062** and **Shiraishi '746**.

In view of the aforementioned amendments and accompanying remarks, claims 1-3, 5, 8, 30 and 33, as amended, are in condition for allowance, which action, at an early date, is requested.

If, for any reason, it is felt that this application is not now in condition for allowance, the

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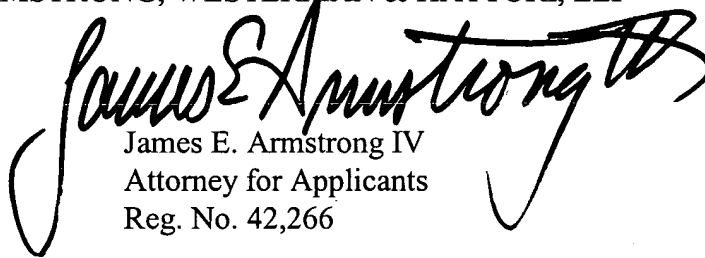
Examiner is requested to contact Applicants' undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

In the event that this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

Respectfully submitted,

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Enclosures: Version with markings to show changes made
Petition for Extension of Time

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IN THE CLAIMS:

Please amend the claims as follows:

1. (Twice Amended) A head assembly comprising:

a mounting surface;

an integrated circuit chip which is mounted on the mounting surface and processes signals;

and

a head slider which is provided with a head and is mounted on the mounting surface,

said integrated circuit chip being covered by a layer,

a height of the integrated circuit chip, including the layer, being lower than a height of the head slider from the mounting surface.

8. (Twice Amended) A disk unit for reading information from and writing information to a disk, comprising:

a head assembly having a mounting surface, a head slider provided with a head and mounted on the mounting surface, and an integrated circuit chip which is mounted on the mounting surface and processes information read from and/or written to the disk via the head,

said integrated circuit chip being covered by a layer,

a height of the integrated circuit chip, including the layer, being lower than a height of the head slider from the mounting surface.

33. (Amended) A unit for reading information from and writing information to a recording medium, comprising:

a head assembly having a mounting surface, a head slider provided with a head and mounted on the mounting surface, and an integrated circuit chip which is mounted on the mounting surface and processes information read from and/or written to the recording medium via the head,

said integrated circuit chip being covered by a layer,

a height of the integrated circuit chip, including the layer, being lower than a height of the head slider from the mounting surface.